

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: M. ISHIKAWARA, et al.
Application No.: 10/526,008
Filed: FEBRUARY 25, 2005
For: METHOD OF MANUFACTURING EPOXY RESIN
COMPOSITION FOR SEMICONDUCTOR ENCAPSULATING
Group AU: 4111
Examiner: David N. Brown II
Confirm. No: 1178

AMENDMENT

Mail Stop: AMEND - FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

September 8, 2008

Sir:

In response to the Office Action mailed May 6, 2008, the period for response having been extended for one (1) month by the attached Petition for Extension of Time, please amend the above-identified application as listed in the following, and as set forth on the following pages:

AMENDMENTS TO THE CLAIMS; and

REMARKS are included following the amendments.